

# PRODUCT DATA SHEET

# TACFlux® 026

## Introduction

**TACFlux® 026** is a no-clean and halide-free flux designed especially for flip-chip and CSP (chip-scale package) attachment. It can be also used for 3D packages (POP). **TACFlux® 026** is designed to accommodate a wide range of reflow temperatures, and is suitable for all SnPb, Pb-free, and high-Pb processes.

## Features

- Excellent wetting
- Wide reflow temperature range
- No-clean
- Low-residue

## Properties

J-STD-004A (IPC-TM-650)	Value
Flux Type Classification	ROLO
Typical Viscosity	330kcps
Typical Acid Number	34
Typical Tack Strength	240g
Reflow Atmosphere	Nitrogen
SIR	Pass
Cleaning	Not needed
Typical Reflow Residual Weight	5%

## Application

**TACFlux® 026** can be applied by printing, dispensing, pin transfer, or dipping.

## Cleaning

**TACFlux® 026** is designed for no-clean applications. If necessary, flux residues can be removed by using a semi-aqueous system, saponified water, alcohols, or other CFC-free alternatives.

## Packaging

**TACFlux® 026** is available in 150g SEMCO cartridges, 10 and 30cc syringes, or 100g jars. Other packaging can be provided to meet specific requirements.

## Storage and Handling

The shelf life of **TACFlux® 026** is 6 months when stored at 0–30°C.

Flux should be allowed to reach ambient working temperature prior to use. Packaging should be labeled with date and time of opening.

## Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Materials Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon, and paste. Indium Corporation's Technical Support Engineers provide rapid response to all technical inquiries.

## Safety Data Sheets

The SDS for this product can be found online at <http://www.indium.com/sds>



This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices. All Indium Corporation's products and solutions are designed to be commercially available unless specifically stated otherwise.

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

## From One Engineer To Another®

Contact our engineers: [askus@indium.com](mailto:askus@indium.com)

Learn more: [www.indium.com](http://www.indium.com)

ASIA +65 6268 8678 • CHINA +86 (0) 512 628 34900 • EUROPE +44 (0) 1908 580400 • USA +1 315 853 4900

Form No. 98185 R2



©2020 Indium Corporation